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 Members of the Texas Instruments Widebus[™] Family 	SN54ABT16657 WD PA(SN74ABT16657 DGG OR DL (TOP VIEW)	
 State-of-the-Art EPIC-IIB[™] BiCMOS Design Significantly Reduces Power Dissipation 		t/R
 Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17 	NC 2 55 10	ODD/EVEN PARITY
 Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C 	GND [] 4 53 [] G 1A1 [] 5 52 [] 1E	B1
 Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise 	$1A2 \begin{bmatrix} 6 & 51 \end{bmatrix} 1E$ $V_{CC} \begin{bmatrix} 7 & 50 \end{bmatrix} V_{CC}$	сс
 Flow-Through Architecture Optimizes PCB Layout 	1A3 8 49 16 1A4 9 48 16 1A5 10 47 16	B4
 High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL}) 	GND 11 46 G	
Package Options Include Plastic 300-mil	1A6 [12 45] 1E	B6
Shrink Small-Outline (DL) and Thin Shrink	1A7 [13 44 [16	
Small-Outline (DGG) Packages and 380-mil		
Fine-Pitch Ceramic Flat (WD) Package	2A1 15 42 2E	
Using 25-mil Center-to-Center Spacings	2A2 16 41 2E	
description		
description	GND 18 39 G	
The 'ABT16657 contain two noninverting octal	2A4 [19 38] 2E 2A5 [20 37] 2E	
transceiver sections with separate parity	2A5 20 37 2E 2A6 21 36 2E	
generator/checker circuits and control signals.	V_{CC} [22 35] V_{CC}	
For either section, the transmit/receive $(1T/\overline{R} \text{ or } T)$	2A7 [23 34] 2E	
$2T/\overline{R}$) input determines the direction of data flow.	2A7 [23 34] 21 2A8 [24 33] 2E	
When $1T/\overline{R}$ (or $2T/\overline{R}$) is high, data flows from the	GND 25 32 G	
1A (or 2A) port to the 1B (or 2B) port (transmit mode); when $1T/\overline{R}$ (or $2T/\overline{R}$) is low, data flows	E	PARITY

from the 1B (or 2B) port to the 1A (or 2A) port (receive mode). When the output-enable $(1\overline{OE} \text{ or })$ 20E) input is high, both the 1A (or 2A) and 1B (or 2B) ports are in the high-impedance state.

NC - No internal connection

30 20DD/EVEN

29 2T/R

П27

NC

20E 28

Odd or even parity is selected by a logic high or low level, respectively, on the 1ODD/EVEN (or 2ODD/EVEN) input. 1PARITY (or 2PARITY) carries the parity bit value; it is an output from the parity generator/checker in the transmit mode and an input to the parity generator/checker in the receive mode.

In the transmit mode, after the 1A (or 2A) bus is polled to determine the number of high bits, 1PARITY (or 2PARITY) is set to the logic level that maintains the parity sense selected by the level at the 1ODD/EVEN (or 20DD/EVEN) input. For example, if 10DD/EVEN is low (even parity selected) and there are five high bits on the 1A bus, then 1PARITY is set to the logic high level so that an even number of the nine total bits (eight 1A-bus bits plus parity bit) are high.



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SN54ABT16657, SN74ABT16657 16-BIT TRANSCEIVERS WITH PARITY GENERATORS/CHECKERS AND 3-STATE OUTPUTS SCBS103B – FEBRUARY 1992 – REVISED JANUARY 1997

description (continued)

In the receive mode, after the 1B (or 2B) bus is polled to determine the number of high bits, the $1\overline{\text{ERR}}$ (or $2\overline{\text{ERR}}$) output logic level indicates whether or not the data to be received exhibits the correct parity sense. For example, if 10DD/EVEN is high (odd parity selected), 1PARITY is high, and there are three high bits on the 1B bus, then $1\overline{\text{ERR}}$ is low, indicating a parity error.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16657 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT16657 is characterized for operation from -40° C to 85° C.

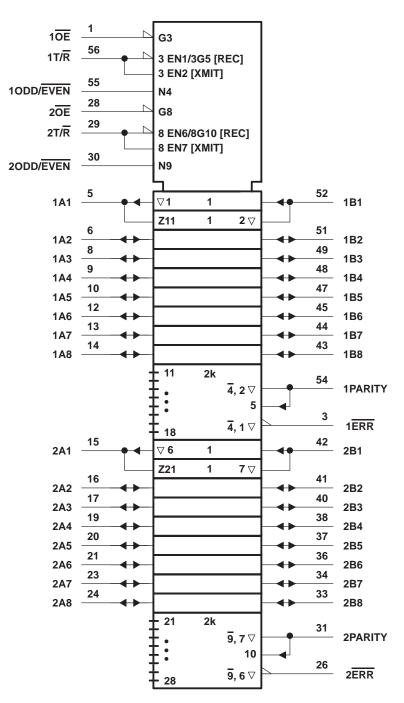
NUMBER OF A OR B		INPU	INPUTS INPUT/OUTPUT			OUTPUTS		
INPUTS THAT ARE HIGH	OE	T/R	ODD/EVEN	PARITY	ERR	OUTPUT MODE		
	L	Н	Н	Н	Z	Transmit		
	L	Н	L	L	Z	Transmit		
0.2.4.6.9	L	L	н	н	н	Receive		
0, 2, 4, 6, 8	L	L	н	L	L	Receive		
	L	L	L	н	L	Receive		
	L	L	L	L	Н	Receive		
	L	Н	Н	L	Z	Transmit		
	L	Н	L	н	Z	Transmit		
4 9 5 7	L	L	н	н	L	Receive		
1, 3, 5, 7	L	L	н	L	н	Receive		
	L	L	L	н	н	Receive		
	L	L	L	L	L	Receive		
Don't care	Н	Х	Х	Z	Z	Z		

FUNCTION TABLE



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logic symbol[†]

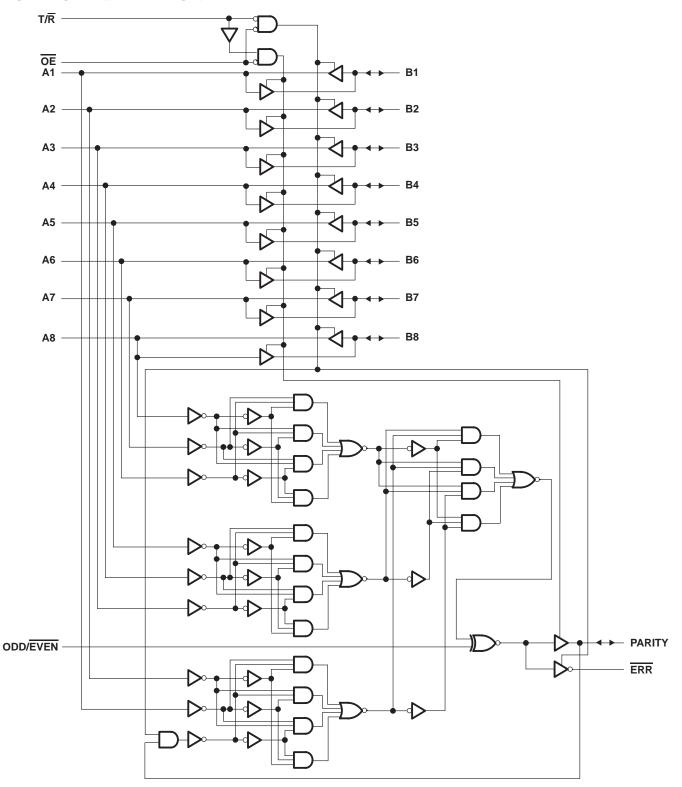


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input clamp current, I_{IK} (V _I < 0) Output clamp current, I_{OK} (V _O < 0) Package thermal impedance, θ_{JA} (see Note 2): DGG package DL package	-0.5 V to 7 V e, V _O
Storage temperature range, T _{stg}	

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT	16657	SN74ABT	16657	UNIT
			MIN	MAX	MIN	MAX	
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	EW	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		00	^C ∨ _{CC}	0	VCC	V
ЮН	High-level output current		رد <i>ک</i>	-24		-32	mA
IOL	Low-level output current		202	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	S.	10		10	ns/V
Т _А	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		7507.00		Т	A = 25°C	;	SN54AB	Г16657	SN74AB1	16657	
PA	RAMEIER	TEST CO	NDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5		
Varia		$V_{CC} = 5 V,$	I _{OH} = -3 mA	3			3		3		V
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v
		VCC = 4.5 V	I _{OH} = -32 mA	2*					2		
Vai		V _{CC} = 4.5 V	I _{OL} = 24 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	v
V _{hys}					100			ĬEI,			mV
1.	Control inputs	V _{CC} = 5.5 V,	VI = VCC or GND			±1		±1		±1	
tı	A or B ports	VCC = 5.5 V,	AL= ACC OLGUD			±100	4	±100		±100	μA
IOZH [‡]	ŧ	V _{CC} = 5.5 V,	V _O = 2.7 V			50	20	50		50	μA
IOZL [‡]		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-50	00	-50		-50	μA
loff		$V_{CC} = 0,$	VI or VO \leq 4.5 V			±100	A.	±450		±100	μA
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
۱ ₀ §		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V _{CC} = 5.5 V,	Outputs high			2		2		2	
ICC	A or B ports	$I_{O} = 0,$	Outputs low			36		36		36	mA
		$V_{I} = V_{CC} \text{ or } GND$	Outputs disabled			2		2		2	
∆ICC¶	I	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	μA
Ci	Control inputs	VI = 2.5 V or 0.5 V			3						pF
Cio	A or B ports	$V_{O} = 2.5 \text{ V or } 0.5 \text{ V}$			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 V$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



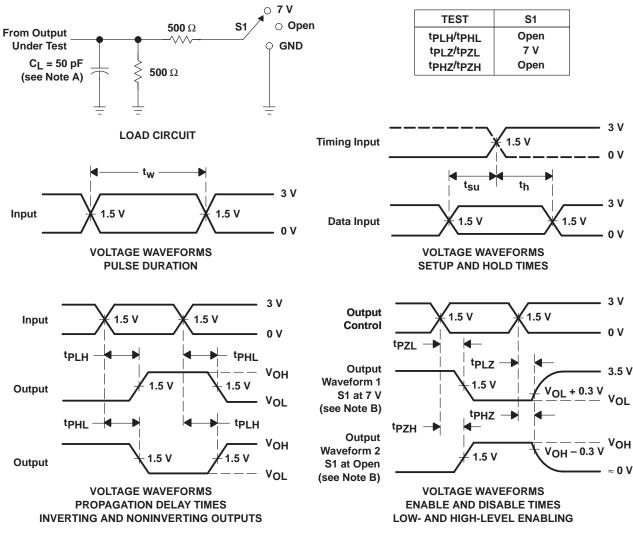
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(T	CC = 5 V A = 25°C	, ,	SN54AB	16657	SN74AB	Г16657	UNIT
		(001-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
^t PHL	AOLP	BUIA	2	3.1	3.9	2	4.5	2	4.3	115
^t PLH	А	PARITY	2	4.6	5.4	2	7	2	6.7	ns
^t PHL	~	FANITI	2	4.3	5.1	2	6.5	2	6.1	115
^t PLH	ODD/EVEN	PARITY, ERR	2	4.6	5.4	2	7	2	6.7	20
^t PHL	ODD/EVEN	PARITI, ERR	2	4.3	5.1	2	6.5	2	6.1	6.1 ns
^t PLH	В	ERR	2	4.6	5.4	2	<u> </u>	2	6.7	ns
^t PHL	В	ERR	2	4.3	5.1	2	č 6.5	2	6.1	115
^t PLH	PARITY	ERR	2	4.6	5.4	Ź	7	2	6.7	ns
^t PHL	FANITI	ERK	2	4.3	5.1	2	6.5	2	6.1	115
^t PZH	OE	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
^t PZL	ÛE	AOIB	2.5	4.3	5.1	2.5	6.2	2.5	6	115
^t PHZ	OE	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
^t PLZ	ÛE	AUB	1.5	3	3.8	1.5	4.7	1.5	4.3	115
^t PZH	OE		2	4	4.9	2	5.8	2	5.6	ns
^t PZL	UE	PARITY, ERR	2.5	4.1	5.1	2.5	6.2	2.5	6	115
^t PHZ	OE	PARITY, ERR	1	3.5	4.5	1	5.5	1	5.4	200
^t PLZ	UE	FARILI, EKR	1.5	3	3.8	1.5	4.7	1.5	4.3 ns	



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



TEXAS NSTRUMENTS

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ABT16657DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16657DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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*All dimensions are nominal

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	•	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16657DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16657DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16657DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16657DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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